

Ho ! ... Ho ! Ho!

IMAPS-UK December newsletter It's that time of year



Christmas is coming along with Snow, a few days Holiday, lots of food and drink and hopefully time to reflect on an interesting but ever changing technology market place or not !

Don't slow down yet ! So where has 2017 gone ? Did you get chance to share with us any of our events? We held 6 good, well received technical events this year and I think I had chance to meet many of our valued members at one or the other of them. Thanks for your support. I hope you have chance to attend one or two of our events next year.... but one in Particular is important - put it in your diary for next year NOW. 2018 is the 50th year of IMAPS-UK and we will celebrate it at the Gala Dinner on April 9 - ahead of the Annual conference and AGM, MicroTech on 10 April. (More about this later)

NEWS:



At this time of year there is not much new to let you know about and

anyway you are probably busy trying to get everything completed in time for a short Holiday break with family and friends. But do please check on what is in this newsletter.

UPDATES ON THE WEBSITE ...

Have you looked at www.imaps.org.uk lately ?

The webmaster has added the latest IMAPS "Advancing Microelectronics" issues ... and he has also added committee minutes to the members downloads section.

There is also the promotional video for IMAPSource on the homepage. This is well worth a visit to understand just what is available for you with your membership of IMAPS-UK.

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2018 marks the nationwide Year of Engineering campaign

The year-long, cross-Government campaign announced on 16 November 2017, aims to celebrate the great contribution that engineering makes to society, and encourage young people to join the profession. The UK Department for Transport is working in partnership with organisations and industry partners across the UK to support events and initiatives throughout the year, which give young people an inspiring experience of modern engineering.

The IET is one of the partners supporting this initiative and will join other Professional Engineering Institutions, plus organisations including London Transport Museum, Network Rail, the Science Museum Group, the RAF and Shell.

EDITORIAL COMMENT (my opinion only !!!)

It is a shame that organisations such as the IET do not seem to recognise the value of Electronic Engineers in this where are the big High Tech companies in this listing ?

MEMS Packaging

The MEMS packaging market's value is growing faster than the MEMS device market's value: respectively, a 16.7% CAGR for packaging versus 14.1% for devices, during the period 2016 - 2022.

MEMS application scope is broad, very fragmented and diversified. Therefore, under its annual report, [Status of the MEMS Industry](#), Yole's MEMS & Sensors team

analyzed more than 200+ applications. Thus, MEMS packaging must always cope with different end-application requirements. It includes for example, protection in different media, hermeticity, interconnection type, and thermal management. This context creates many issues within the packaging industry, which faces different package configurations (open/ closed package).

A good reason to support the "pOp 2" Conference next October

The photonics market is projected to grow from USD 530.52 billion in 2017 to USD 795.54 billion by 2022, at a CAGR of 8.4%. The increased demand for photonics in applications such as displays, information & communication technology, photovoltaic, medical technology & life sciences, measurement & automated vision, lighting, and production technology is expected to drive the growth of the photonics market across the globe. Improved properties, such as better energy efficiency and longer lifespan, contribute to the increased demand for photonics

About Semiconductor Assembly and Testing Services

The number of electronic devices we use in our day-to-day life has been increasing in the past few decades. These devices range from simple media players, smartphones, laptops, and TVs to wearable smart watches and Internet of Things (IoT) devices such as connected thermostats, automated lighting, and remote health monitoring equipment.

Analysts forecast the global semiconductor assembly and testing services (SATS) market to grow at a CAGR of 5.68% during the period 2017-2021.

SATS or outsourced semiconductor assembly and testing (OSAT) refers to the outsourcing of integrated circuit packaging and final product testing to third-party service providers.

One trend in the market is growth of advanced system in package (SiP) modules. A system in a package refers to the technology that enables the integration of several integrated circuits (ICs) within a single package. These packages combine many of the functions performed by different ICs into a single module, which can perform all these operations single-handedly.

For more information please click on:

<https://www.researchandmarkets.com/publication/mla9noo/4416642>

The author of the report recognizes the following companies as the key players in the global semiconductor assembly and testing services market: Amkor Technology, ASE Group, Jiangsu Changjiang Electronics Technology (JCET), Powertech Technology, and Siliconware Precision Industries (SPIL).

Other Prominent Vendors in the market are: Chipbond Technology, ChipMOS TECHNOLOGIES, FormFactor, Formosa Advanced Technologies, King Yuan ELECTRONICS, Lingsen Precision Industries, PSi Technologies, SIGNETICS, Tessolve Semiconductor, Tianshui Huatian Technology, Unisem, and UTAC.

ELECTRONIC MATERIALS

Optimat has been appointed by Innovate UK to undertake a Materials Landscaping Study, the aim of which is to understand the size, shape and capabilities of the materials industry in the UK and individual sub-sectors within it. This will be used by the Advanced Materials teams in Innovate UK and BEIS to better target government innovation support and investment to help the industry grow.

One of the main outputs of this study will be a comprehensive database of materials companies across the UK and Optimat are keen to work with relevant organisations (such as IMAPS-UK) to help identify as many companies as possible and to ensure that each sub-sector of the materials industry is well represented. If you would consider contributing to this landscaping study by providing any electronic materials company data you have or, indeed, any other information that you feel may be useful, please contact:

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Director, Optimat Ltd.,

Email: iain.weir@optimat.co.uk



Following the success of the RelPack conference last month, we have been asked to hold a workshop on the Afternoon before the MicroTech Conference (Monday 9 April- Afternoon) on the 'Science of Bond testing'



It will be run by Bob Sykes of XYZTec.

Full details and registration information will be on the website in Early January

So..... Have you got next year's diary to hand ?

.... then **BOOK THE DATE NOW**

The Workshop followed by a Gala Dinner on **9 April** and the Conference/AGM on **10 April**.



Membership of IMAPS-UK



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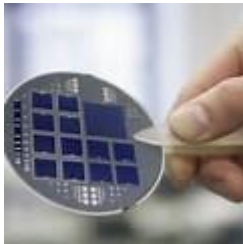
MORE EVENTS



"APCS 2018"

8 February 2018 - At the "Studio" Birmingham.

Advanced Packaging for Compound Semiconductors, will be held in Birmingham, jointly with the KTN. This workshop/colloquium is aimed at supporting the needs of the new CSA Catapult.



The programme is now on the website you can also register via the website and just in case you missed out before, this Packaging workshops is already getting booked up and the number of places is limited to 50 people

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DATES for your Diary

IMAPS-UK EVENTS BEING PLANNED FOR 2018 ARE:

21 June 2018 - at NPL - Workshop/Colloquium about Substrates

6 September 2018 - A "basic" Packaging Workshop

23 October 2018 "pOp II" or "pOp 2" - The 2nd IMAPS-UK Photonics and Opto Packaging Conference.

- A conference and Table top exhibition at South Devon College, Torbay - supported by the Torbay High Tech Forum.

6 December 2018 - Packaging for Space Applications

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And in other IMAPS Europe Chapters, please note:

IMAPS Nordic and IEEE EPS are again organizing together the NordPac conference and exhibition. This will be held 12 – 14, June 2018 in Oulu, Finland.

Please reserve the dates in your calendar and budget. You can find the call for papers on the IMAPS Nordic website - www.nordpac.org

SOME OTHER EVENTS >>>>>

SEMI European 3D Summit to Spotlight the Trends Driving 3D Semiconductor Development

Meet leading companies, learn about new technologies, and connect with the people driving the future of 3D Integration design and manufacturing at the SEMI European 3D Summit, 22-24 January 2018, in Dresden, Germany.

See the full program [here](#).

Always book your place at the events in good time

Well that is almost enough for this year, it just remains for your IMAPS-UK Committee and myself wish you all a successful and prosperous 2018.

I look forward to connecting with you all soon



Best wishes,
Andy Longford
IMAPS-UK Secretariat

PLEASE NOTE THAT THE IMAPS-UK OFFICE WILL BE CLOSED FROM Friday 22 December UNTIL Tuesday 2 January 2018



This e-mail newsletter has been sent to you by
IMAPS-UK Secretariat - Andy Longford - on
Friday 15 December 2017



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